

SEMICONDUCTOR CHIP MOUNTING APPARATUS AND MOUNTING METHOD

ABSTRACT OF THE DISCLOSURE

A semiconductor chip mounting apparatus able to raise the positional accuracy when mounting a semiconductor chip on a package including a stage on which the substrate is carried, a visible light source for directly illuminating the substrate from above the stage, a semiconductor chip conveying means for holding from one surface the semiconductor chip comprised of silicon formed to a thickness through which visible light can pass and conveying it on the substrate carried on the stage, a capturing means arranged at a position facing the stage and capturing visible light passing through the semiconductor chip held by the semiconductor chip conveying means so as to capture patterns formed on the substrate carried on the stage and the semiconductor chip, and a positioning means for positioning the semiconductor chip on the substrate based on the patterns of the substrate and the semiconductor chip captured by the capturing means.